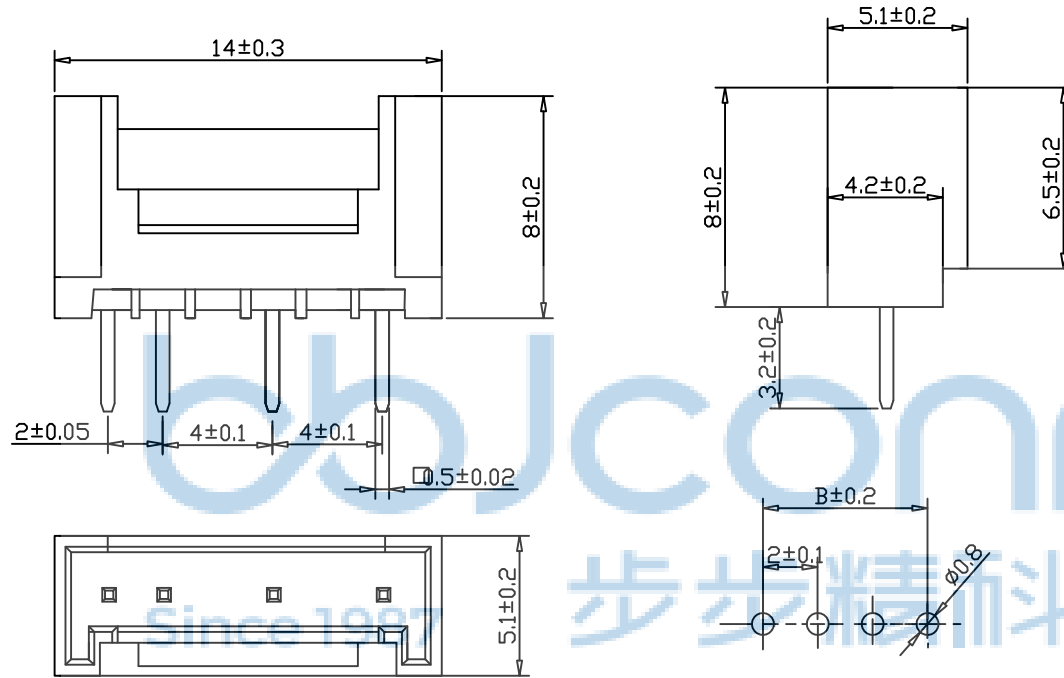


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0				

使用温度范围 (Ambient temperature Range):  $-25^{\circ} \sim +85^{\circ}$   
 适用线规 (Applicable Wires): AWG 28#~22#  
 适用基板厚度 (Applicable PCboard thickness):  $0.8\text{mm} \sim 1.6\text{mm}$   
 额定电压 (Voltage rating): 250V AC, DC  
 额定电流 (Current rating): 2A  
 接触电阻 (Contact Resistance):  $\leq 0.01 \Omega$   
 绝缘电阻 (Insulation Resistance):  $\geq 1000M \Omega$   
 耐压 (Withstand Voltage): 800V/min  
 焊接温度 (Soldering pot):  $230 \pm 5^{\circ}\text{C}$   
 材料 (Material)  
 1. 基座: 白色 PA66 UL94V0  
 2. 基座: 米色 增强尼龙 UL94V0  
 3. 插针: 黄铜

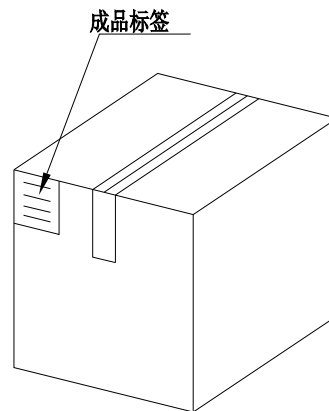
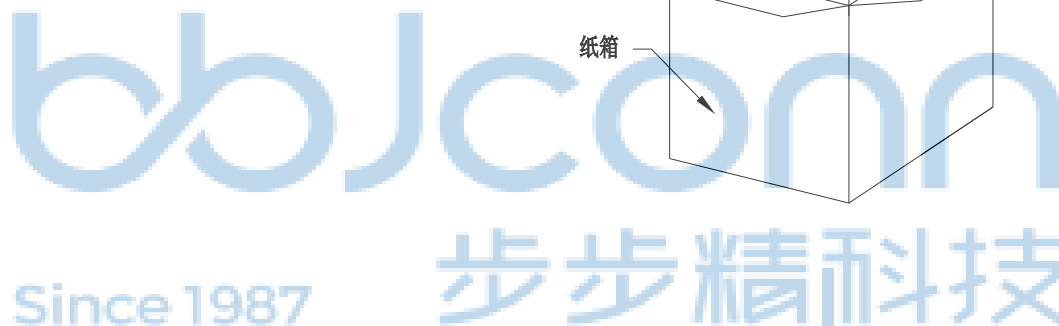
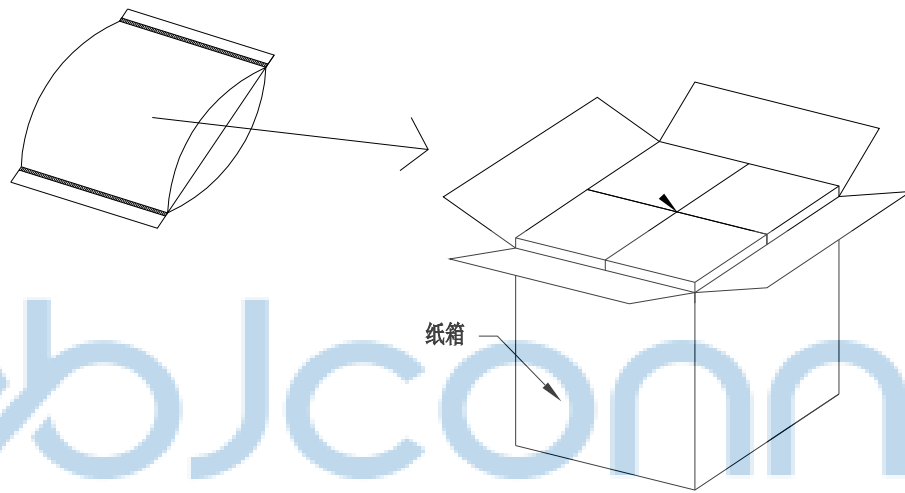


未注公差				
范围	>0-3	>3-18	>18-50	>50-100
公差	±0.15	±0.2	±0.3	±0.5

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PDWG.NO: 0102-1	DR. SGF	APPD. JM_Zheng	CHKD. LYX		

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0				

PE袋规格:\*\*\*X\*\*\* (以实际出货为准)



1. 包装要求:

- 1.1 每PE袋包装 2000 pcs;
- 1.2 每1袋放一小纸盒;
- 1.3 每20个小纸盒放一个纸箱, 共计40000PCS
- 1.4 纸箱外贴上标签



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APPD.	JM_Zheng	PJ. NO.: WT.11.13-11-1002		SIZE: A4   DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES   MAT'L.: SEE NOTES		SCALE: N/A   REV.: A0   UNIT: mm   PAGE: 2/2	
PDWG.NO:	0102-1	DR.	SGF		